

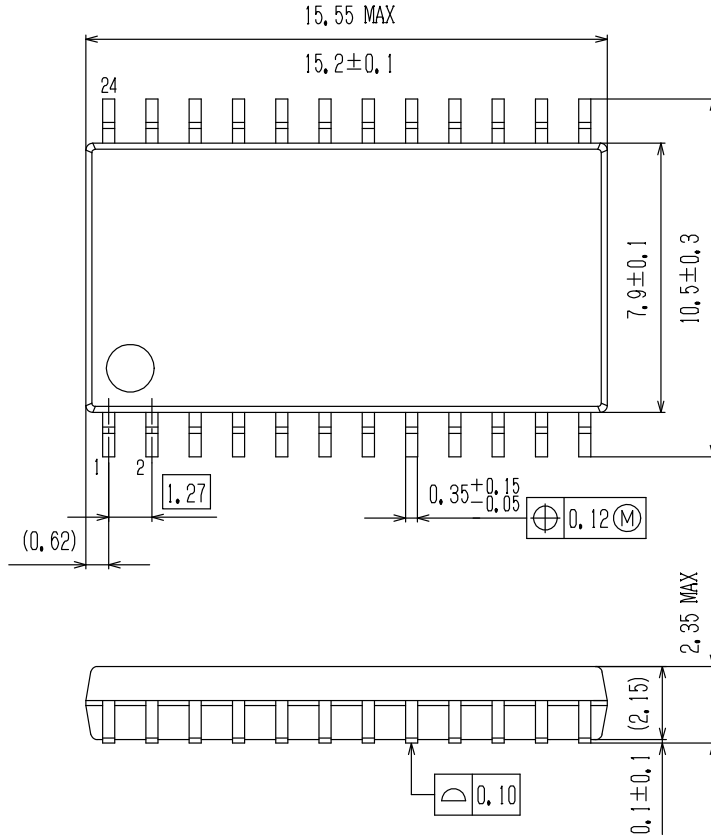
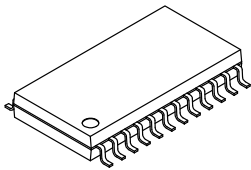
**MECHANICAL CASE OUTLINE**  
**PACKAGE DIMENSIONS**

ON Semiconductor®

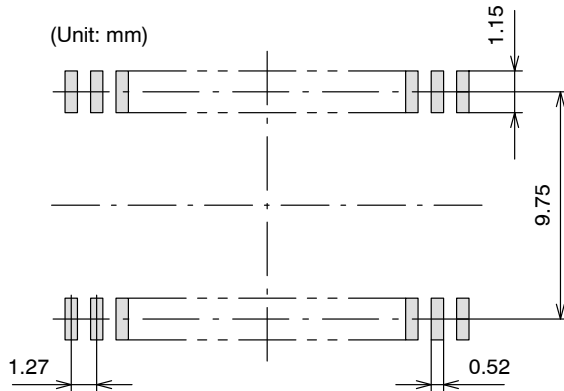


**SOIC24 W / MFP24 (375 mil)**  
**CASE 751CF**  
**ISSUE A**

DATE 08 NOV 2013



**SOLDERING FOOTPRINT\***



**GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code  
 Y = Year  
 M = Month  
 DDD = Additional Traceability Data

NOTE: The measurements are not to guarantee but for reference only.

\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>SOIC24 W / MFP24 (375 MIL)</b>	<b>PAGE 1 OF 2</b>

